Statement of Materials, Construction

LEAD-FREE -- 32L QFN -- TABLE OF MATERIAL DECLARATION								
No.	Component Name	Material Name	Component Weight (grams)	Materials Analysis (Element/Compound)	CAS Number	Material Mass (grams)	Material Weight % (of Total Pkg.)	Material Weight % (of Component)
1	Leadframe	Copper Alloy (with Silver plate)	0.00446	Cu	7440-50-8	0.00423	6.04	94.86
				Mg	7439-95-4	0.00001	0.01	0.18
				Ni	7440-02-0	0.00014	0.20	3.20
				Si	7440-21-3	0.00003	0.05	0.73
				Silver (Ag)	7440-22-4	0.00005	0.07	1.04
2	Die	Silicon Chip	0.00442	Si	7440-21-3	0.00442	6.30	99.99
3	Die Attach Material	Conductive Epoxy	0.00010	Silver (Ag)	7440-22-4	0.00008	0.11	76.00
				Functionalized Urethane	Proprietary	0.00001	0.01	8.00
				Diester Resin	Proprietary	0.00001	0.02	10.50
				Epoxy Resin	Proprietary	0.00001	0.01	5.50
4	Wire	Gold	0.00034	Au	7440-57-5	0.00034	0.48	99.99
5	Lead Finish	Tin	0.00003	Sn	7440-31-5	0.00003	0.05	100
6	Encapsulation	Epoxy Resin	0.06072	Fused Silica	60676-86-0	0.05295	75.56	87.20
				Epoxy Resin A	Proprietary	0.00121	1.73	2.00
				Epoxy Resin B	Proprietary	0.00182	2.60	3.00
				Phenol Resin A	Proprietary	0.00182	2.60	3.00
				Phenol Resin B	Proprietary	0.00182	2.60	3.00
				Metal Hydoxide	Proprietary	0.00091	1.30	1.50
				Carbon Black	1333-86-4	0.00018	0.26	0.30
Total Package Weight =			0.07007					

Note: Component Weight based on assembly of generic parts.

Conclusion:

The analysis table above shows that this package meets the following RoHS requirements for EACH PACKAGE COMPONENT (mold compound, lead frame, etc.)

	Maximum Allowable Limit (ppm)	Maximum Allowable Limit (wt %)
Lead	1000 ppm	0.10%
Mercury	1000 ppm	0.10%
Cadmium	100 ppm	0.01%
Hexavalent Chromium	1000 ppm	0.10%
Polybrominated Biphenyls (PBB)	1000 ppm	0.10%
Polybrominated Biphenylethers (PBDE)	1000 ppm	0.10%